

## Flex-Rigid Pcb

Range and specs of flex-rigid pcb

Types of Products	Item	Technical Capacity	Mass Production (MP)	Sample
Base Board Flex-Rigid PCB, and FPC		HDL Multilayer PCB, Buried/Blind Via Board, High Frequency Board,		Aluminum
Aluminum Base Board Flex-Rigid PCB FPC,		HDL Multilayer PCB, Buried/Blind Via Board, High Frequency Board,		FR-4,Alluminum,
Non-halogen, Lead-free Compatibility ,High TG, High		Teflon Board, and HDI	Material	FR-4,Alluminum, Non-halogen,
Lead-free Compatibility ,High TG, High		CTI,CEM-1,CEM-3	layers	2-12 Layers
2-14 Layers	Conductor Width/ Space of the Inner Layer	4/4mil		4/3mil or 3/4mil
	Conductor Width/ Space of the Outlayer Layer	4/4mil	4/3mil 3/4mil	Board Width of
the Inner Layer	0.1-1.6mm	0.075-1.6mm	Hole Diameter	0.2mm
0.15mm	Ratio of Depth against Diameter	8:1	10:1	Maximum Dimension
630*530mm	630*530mm		Interior Copper Width	18-140um
210um	Exterior Copper Width	12-210um	12-210um	Minimum Width of
the Welding Ring	0.13mm	0.10mm	Minimum Width of Bridge with Solder Mask	
0.08mm	0.05mm	Minimum Solder Resist Window	0.05mm	0.03mm
	Tolerance of Solder Resistance	±10%	±8%	Board Thickness
0.25mm^3.4mm	0.25mm^3.4mm		Outline Process Precision	±0.1mm
±0.08mm	Surface Treatment	HAL, Plated Nickel/ Gold, Immersion Gold, Lead-Free		
Compatibility OSP, Carbon Ink, Protective Adhesive, Tin Plating ,Immersion Silver, Immersion		Finger, Immersion Silver + Thickly Plated Gold Finger		Tin, Thickly Plated
Gold Finger, Immersion Gold+ Thickly Plated Gold		Finger, Immersion Silver + Thickly Plated Gold Finger		
HAL, Plated Nickel/ Gold, Immersion Gold, Lead-Free Compatibility OSP, Carbon Ink, Protective Adhesive, Tin Plating		,Immersion Silver, Immersion Tin, Thickly Plated Gold Finger, Immersion Gold+ Thickly Plated Gold		Finger,
,Immersion Silver, Immersion Tin, Thickly Plated Gold Finger, Immersion Silver + Thickly Plated Gold Finger, Immersion Gold + OSP				